

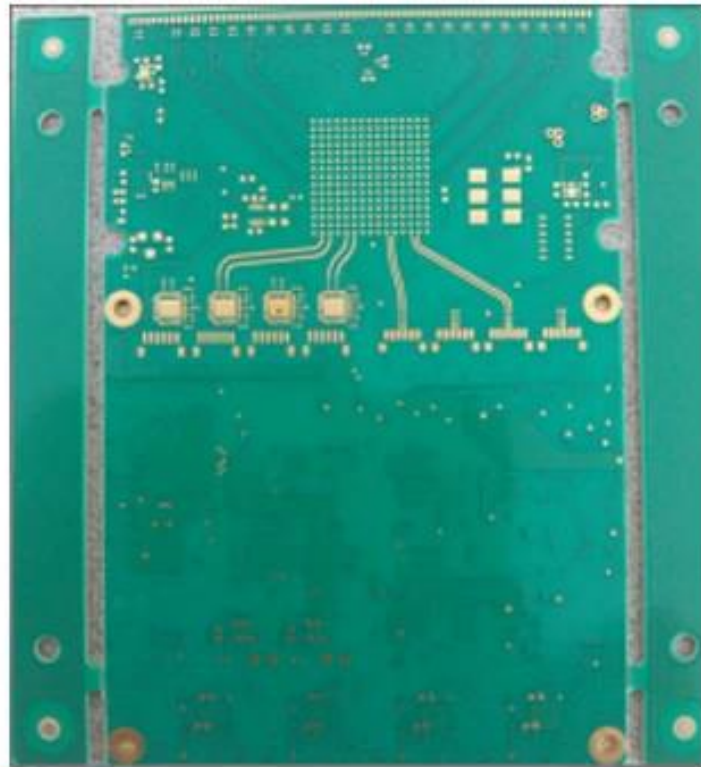
COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

This PN required 10% impedance, 8mil laser drill, POFV, stacked via, laser blind via drill thru 6mil dielectric and plug and plating flat via

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

Layer structure

| Custom Info Lyr | Image | Foil | Name |
|-----------------|-------|-------|-------------------------------------------|
| COMP | | 0.5oz | Foil 1/2oz(RTF) |
| 6+/-0.9mil | | | R-5670K 1080 RC64% |
| | | | R-5670K 1080 RC64% |
| L2 | | 0.5oz | Foil 1/2oz(RTF) |
| 3.9+/-0.7mil | | | R-5670K 3313 RC54% |
| L3 | | 0.5oz | |
| L4 | | 0.5oz | R-5775K 0.200mm H/H 42.5"49"(3313*2)(RTF) |
| | | 0.5oz | |
| | | | R-5670K 1080 RC64% |
| 6.9+/-1.5mil | | | R-5670K 3313 RC54% |
| | | 0.5oz | R-5775K 0.100mm H/H 42.5"49"(3313*1)(RTF) |
| L5 | | 0.5oz | |
| L6 | | | R-5670K 3313 RC54% |
| | | | R-5670K 1080 RC64% |
| 6.9+/-1.5mil | | 0.5oz | R-5775K 0.200mm H/H 42.5"49"(3313*2)(RTF) |
| L7 | | 0.5oz | |
| L8 | | | R-5670K 3313 RC54% |
| 3.9+/-0.7mil | | | |
| L9 | | 0.5oz | Foil 1/2oz(RTF) |
| | | | R-5670K 1080 RC64% |
| 6+/-0.9mil | | | R-5670K 1080 RC64% |
| | | | |
| SOLD | | 0.5oz | Foil 1/2oz(RTF) |





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